



Kulicke & Soffa Receives New Order for High-Performance Die Attach Equipment – APAMA™ DA

February 9, 2018

SINGAPORE--(BUSINESS WIRE)--Feb. 9, 2018-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) (“Kulicke & Soffa”, “K&S” or the “Company”), announced it has received a new order of its high-performance die attach equipment, APAMA™ DA, under the APAMA *Series* of solutions. The APAMA™ DA, offering both flip chip and epoxy capabilities, were ordered by a leading camera module manufacturer. This order continues the growth of the APAMA™ DA installed base since its June 2017 release. Growing market demand for this unique epoxy glass-attach solution, validates Kulicke & Soffa’s development efforts and provides a compelling response to the industry’s advanced packaging challenges.

With the rapid growth of connected devices and smartphones the demand for camera modules, memory and sensing devices has expanded significantly. Designed to stay ahead of technology trends, APAMA™ DA provides market leading throughput for the most complex and high-accuracy applications.

The APAMA™ DA features the latest parallel processing and post-pick alignment technology delivering industry leading throughput, while also providing exceptional process repeatability and flexibility. Its patented dynamic calibration technology allows continuous recalibration ensuring critical placement stability and consistency for the most demanding, high-volume production environments.

Shubneesh Batra, K&S’s Vice President of Advanced Packaging Business Unit, said, “K&S continues to rapidly expand its portfolio of Advanced Packaging tools driving new solutions to the most challenging and demanding applications. The recent market success serves as a testament to our dedication and commitment to support and resolve our customers’ most challenging assembly requirements.”

The Company’s full line of solutions can be found [here](#).

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. (www.kns.com)

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